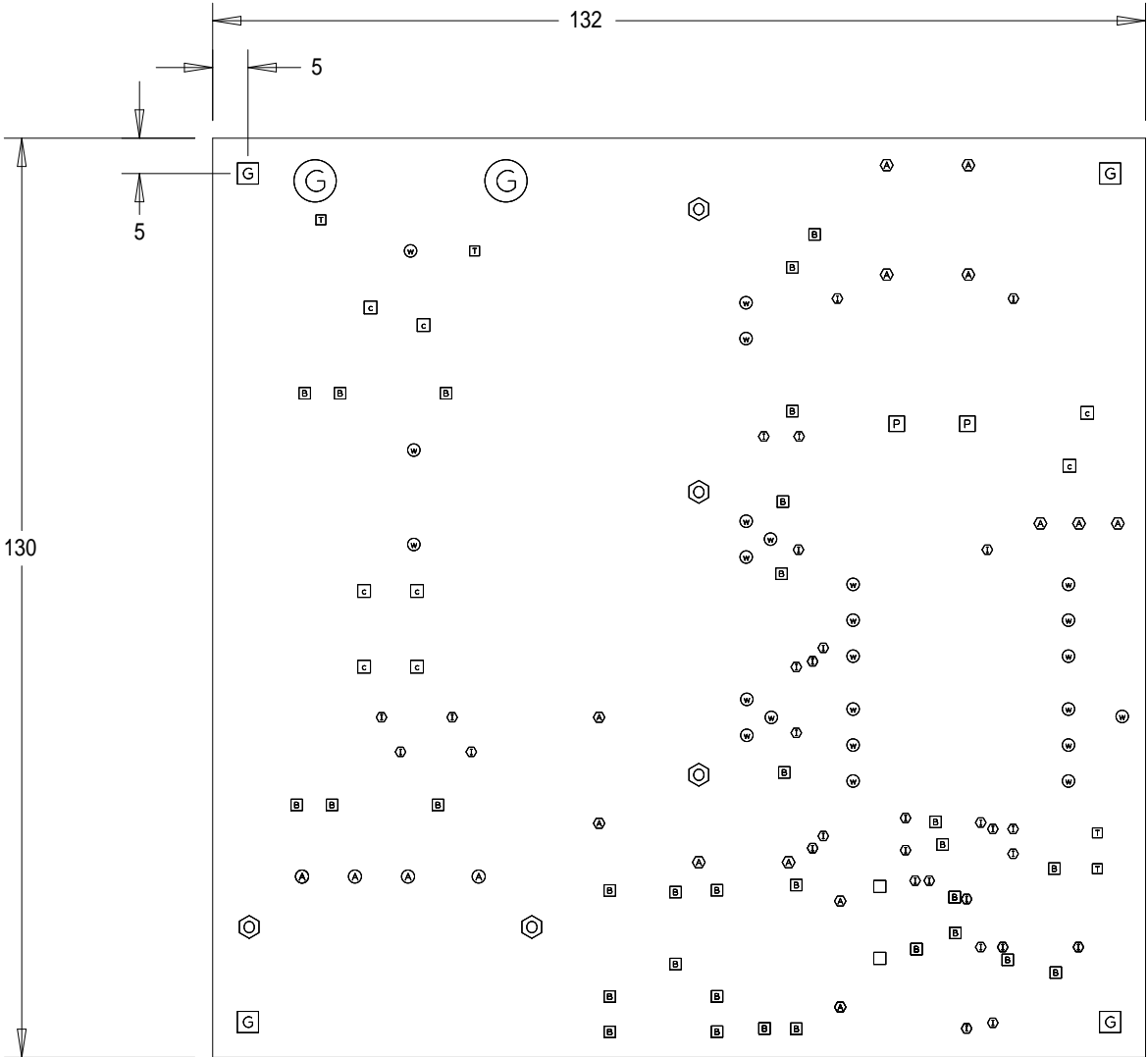



SPEC:

COMPLIANT RoHS DIRECTIVE 2011/65/UE

MATERIAL	FR4 IMPROVED (low CTE)
BOARD THICKNESS	1.6mm /63mils
STACKUP	SF /1LAYER
MINIMAL GAP	200um /8mils
MINIMAL SLIVER	200um /8mils
COPPER THICKNESS	70um(2oz)
FINISH THICKNESS	CHEMICAL NiAu
SOLDER MASK	GREEN BOT
SILKSCREEN	WHITE TOP&BOT
ALL BOARD ELECTRICALLY TESTED	
MANUFACTURE 'S LOGO & DATECODE MARKED ON BOTTOM SOLDERMASK	

DRILL CHART: TOP to BOTTOM			
ALL UNITS ARE IN MILLIMETERS			
FIGURE	SIZE	PLATED	QTY
⌀	0.8	PLATED	30
⊞	1.0	PLATED	31
□	1.1	PLATED	2
⊞	1.2	PLATED	8
⊞	1.4	PLATED	4
⊞	1.6	PLATED	24
⊞	1.6	PLATED	4
⊞	1.8	PLATED	9
⊞	1.9	PLATED	4
⊞	2.2	PLATED	2
⊞	3.2	PLATED	5
⊞	3.0	NON-PLATED	4
⊞	6.0	NON-PLATED	2



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indice	Description		Date
Controle par :		Autorise par:	
 ON semiconductor		Definition CUT DRILL DRAWING PLAN PRECAGE DETOURAGE	
		Subc. <b>DYPE TECH</b>	Dessine: e B
Board: <b>NCP1655 A TLS</b>		Echelle: 1/1	Pages: 1/3
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